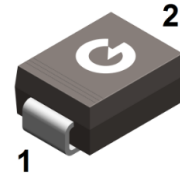


Features

- Metal silicon junction, majority carrier conduction
- High forward surge current capability
- Low forward voltage drop
- High temperature soldering guaranteed: 260°C @ 10s
- Robust guarding for over voltage protection
- RoHS compliant with Halogen-free
- Qualified to AEC-Q101 Standards

HF



SMB

Mechanical Data

- Case: SMB
- Molding compound: UL flammability classification rating 94-0
- Terminals: Tin-plated; solderability per MIL-STD-202, Method 208
- Polarity: Color band denotes cathode end

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
TSS25	SMB	3000 pcs / Tape & Reel	SS25
TSS26	SMB	3000 pcs / Tape & Reel	SS26

Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter	Symbol	TSS25	TSS26	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	50	60	V
RMS Reverse Voltage	V _{RMS}	35	42	V
DC Blocking Voltage	V _{DC}	50	60	V
Average Forward Output Current	I _{F(AV)}	2.0		A
Peak Forward Surge Current, 8.3ms Single Half-Sine-Wave	I _{FSM}	50		A

Thermal Characteristics

Parameter	Symbol	TSS25	TSS26	Unit
Thermal Resistance Junction-to-Air ^{*1}	R _{θJA}	60		°C/W
Thermal Resistance Junction-to-Case ^{*1}	R _{θJC}	23		°C/W
Thermal Resistance Junction-to-Lead ^{*1}	R _{θJL}	25		°C/W
Thermal Resistance Junction-to-Air ^{*2}	R _{θJA}	160		°C/W
Thermal Resistance Junction-to-Lead ^{*2}	R _{θJL}	36.5		°C/W
Operating Junction Temperature Range	T _J	-55 ~ +150		°C
Storage Temperature Range	T _{STG}	-55 ~ +150		°C

Electrical Characteristics (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage	$V_{(BR)}$	$I_R = 100\mu\text{A}$, TSS25	50	-	-	V
		$I_R = 100\mu\text{A}$, TSS26	60	-	-	V
Forward Voltage *3	V_F	$I_F = 2\text{A}$	-	-	0.65	V
Maximum Peak Reverse Current *4	I_R	Rated V_R , $T_J = 25^\circ\text{C}$	-	-	100	μA
		Rated V_R , $T_J = 100^\circ\text{C}$	-	-	10	mA
Diode capacitance	C_J	$V_R = 4\text{V}$, $f = 1\text{MHz}$	-	98	-	pF

Notes:

1. The data tested by surface mounted on p.c.b. with 10 mm x 20 mm x 0.1 mm copper pad area
2. The data tested by surface mounted on a minimum recommended FR-4 board
3. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 1\%$
4. The data tested by pulsed, pulse width $\leq 40\text{ms}$

Ratings and Characteristic Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

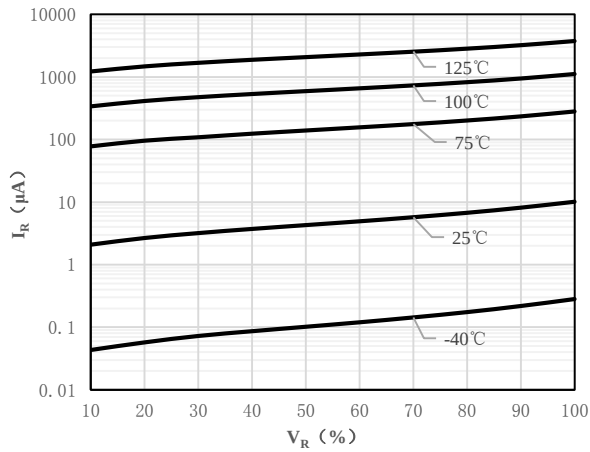


Fig 1 Typical Reverse Characteristic

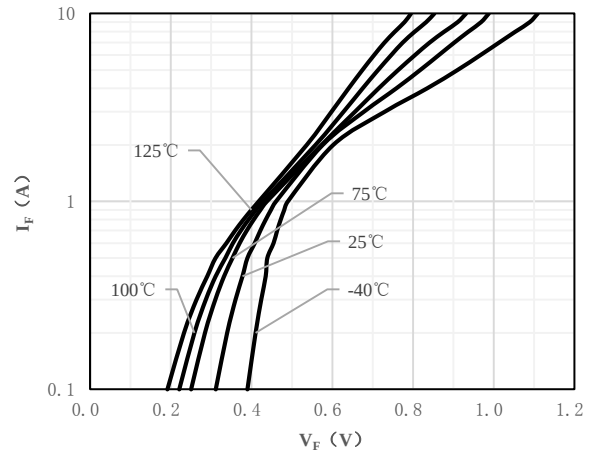


Fig 2 Typical Forward Characteristics

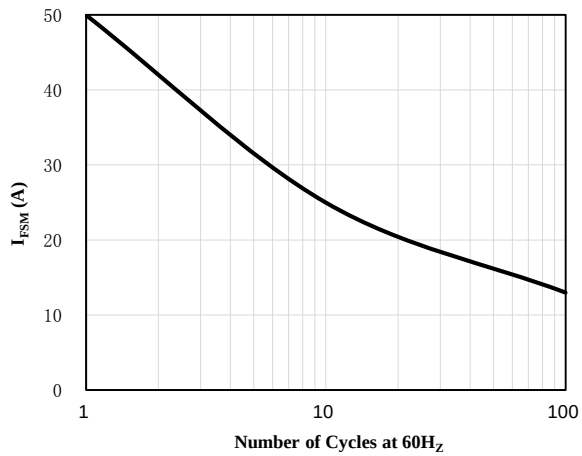


Fig 3 Surge Current Derating Curve

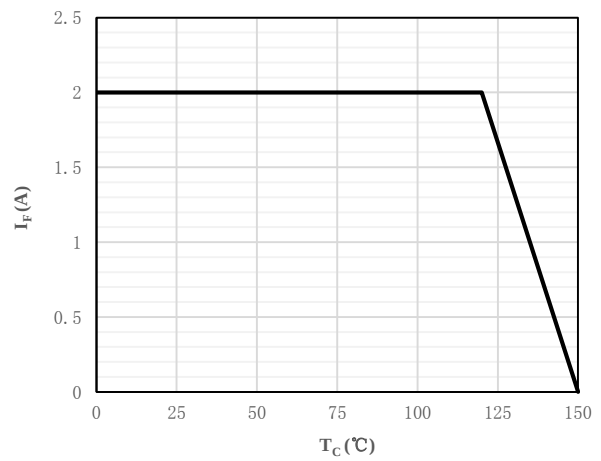
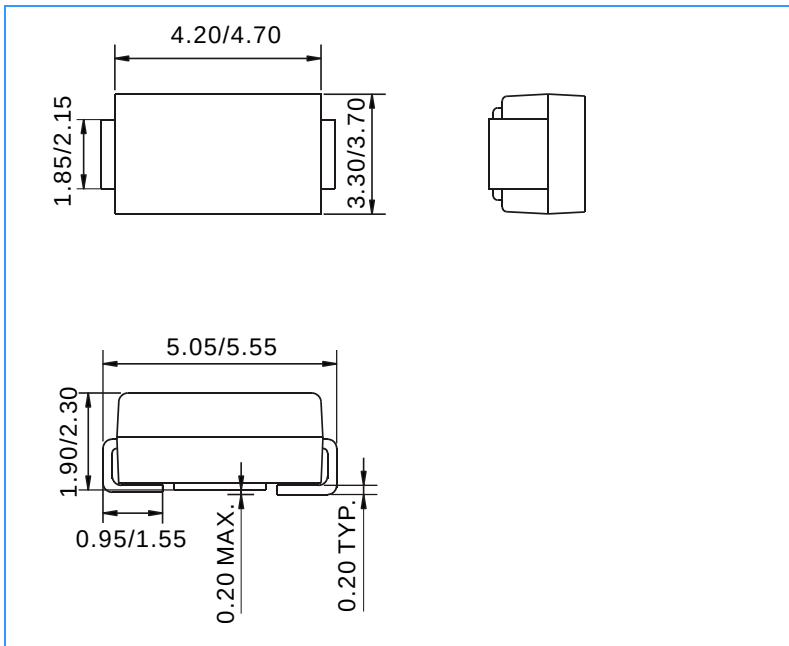


Fig 4 Forward Current Derating Curve

Package Outline Dimensions (Unit: mm)



Mounting Pad Layout (Unit: mm)

